ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information														
Company name*			Company unique ID			Unique ID Authority				Response Date*				
ısemi										2025-07-15				
ontact Name	Title - Conta	Title - Contact			Phone - Contact*				Email - Contact*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - R			resentative			Phone - Representative*				Email - Representative*				
roduct-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number			Number Mfr Item Name			Effective Da	Date Version Manufacturing Site		W	'eight*	UOM	Unit Type		
	MT9P0 DP1	C9P006I12STCU- 5 MP 1/2.5 CIS				2025-07-15			258.99		mg	Each		
Ianufacturing Proccess Informa	ation					•								
Terminal Plating / Grid Array M	Material Terminal Base Alloy		Alloy	J-STD-020 MS	L Rating Peak		k Process Body Temperature Max Time at Pea		Гіте at Peak	Temperature Number of Reflow Cycles		eles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy	U Alloy 4			260 C		С	30	seco		s 3		
omments														
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	59.5	mg		Misc.	proprietary data			mg
			Supplier	Silicon (Si)	7440-21-3		58.6848	mg
			Supplier	Aluminum (Al)	7429-90-5		0.589	mg
Die Attach	2.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.825	mg
			Supplier	Ethylene Glycol	107-21-1		0.022	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.066	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.462	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.825	mg
Imaging Lens	55.32	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.766	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.766	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.766	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.766	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2766	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.766	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.766	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		38.4474	mg
Lid Attach	2.4	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.7584	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1248	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.7584	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.7584	mg
Mold Compound-Black	55.01	mg		Phenolic Resin	proprietary data		8.2515	mg
			Supplier	Oxirane	39817-09-9		8.2515	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.6503	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5501	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.2064	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1002	mg
Substrate and Solder Mask	84.3	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		17.5934	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.0875	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2698	mg
			Supplier	Acetophenone Derivative	Proprietary Data		1.627	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2698	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2698	mg
			В	Nickel (Ni)	7440-02-0	1.0285	mg
			Supplier	Gold (Au)	7440-57-5	0.2192	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.2793	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	10.8578	mg
			Supplier	Copper (Cu)	7440-50-8	39.385	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.4131	mg
Wire Bond - Au	0.26	mg	Supplier	Gold (Au)	7440-57-5	0.26	mg